

## Abstract

An object is to provide a cleaning member for semiconductor apparatus which can easily remove, without fail, foreign matters adherent to inner parts of a semiconductor apparatus, can bear a clearly readable mark for lot management, and can be prevented from generating particles upon contact with the holding part of a wafer case.

A cleaning member for semiconductor apparatus, characterized in that the cleaning member comprises a wafer 1 and formed on at least one side thereof a cleaning layer 2 made of a heat-resistant resin formed by thermally curing a poly(amic acid), and that the cleaning layer 2 has a part 12 where a wafer surface is exposed; and in particular a cleaning member for semiconductor apparatus having the constitution described above wherein that part 12 in the cleaning layer 2 in which a wafer surface is exposed is a part where the cleaning layer has been removed throughout the whole circular area having a given width ranging from the peripheral edge of the wafer toward the center thereof.